

Product / Package Information

Package	LFCSP - Isolated Backside
Body Size (mm)	4 X 4 X 0.85 (2.34 EP)
Lead Count	24
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.23E-02	86.91	869100	29.56	295615
Thermosets	Epoxy & Phenol Resin	Proprietary	1.81E-03	12.78	127800	4.35	43470
Other inorganic materials	Carbon black	1333-86-4	4.39E-05	0.31	3100	0.11	1054
Subtotal			1.42 E-02	100.00	1000000	34.01	340139

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.21 E-02	97.5	975000	53.05	530477
Copper & its alloys	Iron	7439-89-6	5.32 E-04	2.35	23500	1.28	12786
Copper & its alloys	Zinc	7440-66-6	2.72 E-05	0.12	1200	0.07	653
Copper & its alloys	Phosphorus	7723-14-0	6.80 E-06	0.03	300	0.02	163
Subtotal			2.27 E-02	100.00	1000000	54.41	544079

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.00 E-04	100.0	1000000	1.20	12011

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	7.30 E-04	100.0	1000000	1.75	17535

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.00 E-04	100.0	1000000	1.20	12011

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.84 E-03	100.0	1000000	6.82	68220

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Thermoset	Epoxy Resin	Proprietary	1.65 E-04	66.00	660000	0.40	3963
Others	Polymeric Resin	Proprietary	8.50 E-05	34.00	340000	0.20	2042
Subtotal			2.50 E-04	100.0	1000000	0.60	6005

Package Totals			Weight (g) 4.16 E-02			Percentage (%) 100.00	PPM 1000000
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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